

November 2013

# FQP10N20C / FQPF10N20C

# N-Channel QFET<sup>®</sup> MOSFET 200 V, 9.5 A, 360 m $\Omega$

## **Features**

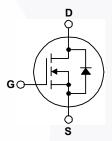
- 9.5 A, 200 V,  $R_{DS(on)}$  = 360 m $\Omega$  (Max.) @  $V_{GS}$  = 10 V,  $I_D$  = 4.75 A
- · Low Gate Charge (Typ. 20 nC)
- Low Crss (Typ. 40.5 pF)
- · 100% Avalanche Tested

## Description

This N-Channel enhancement mode power MOSFET is produced using Fairchild Semiconductor's proprietary planar stripe and DMOS technology. This advanced MOSFET technology has been especially tailored to reduce on-state resistance, and to provide superior switching performance and high avalanche energy strength. These devices are suitable for switched mode power supplies, active power factor correction (PFC), and electronic lamp ballasts.







# MOSFET Maximum Ratings T<sub>C</sub> = 25°C unless otherwise noted.

Symbol	Parameter		FQP10N20C	FQPF10N20C	Unit	
V <sub>DSS</sub>	Drain to Source Voltage		200		V	
I <sub>D</sub>	Drain Current	-Continuous (T <sub>C</sub> = 25°C)	-Continuous (T <sub>C</sub> = 25°C) -Continuous (T <sub>C</sub> = 100°C)		9.5 *	Α
	Drain Current	-Continuous (T <sub>C</sub> = 100°C)			6.0 *	Α
I <sub>DM</sub>	Drain Current	- Pulsed	(Note 1)	38	38 *	Α
V <sub>GSS</sub>	Gate to Source Voltage		± 30		V	
E <sub>AS</sub>	Single Pulsed Avalanche Energy (Not		(Note 2)	210		mJ
I <sub>AR</sub>	Avalanche Current		(Note 1)	9.5		Α
E <sub>AR</sub>	Repetitive Avalanche Energy (Note		(Note 1)	7.2		mJ
dv/dt	Peak Diode Recovery dv/dt (Note 3)		(Note 3)	5.5		V/ns
$P_{D}$	Dower Dissinction	(T <sub>C</sub> = 25°C)		72	38	W
	Power Dissipation	- Derate above 25°C		0.57	0.3	W/°C
T <sub>J</sub> , T <sub>STG</sub>	Operating and Storage Temperature Range		-55 to +150		°C	
T <sub>L</sub>	Maximum Lead Temperature for Soldering Purpose, 1/8" from Case for 5 Seconds		300		°C	

<sup>\*</sup>Drain current limited by maximum junction temperature

#### **Thermal Characteristics**

Symbol	Parameter	FQP10N20C	FQPF10N20C	Unit
$R_{\theta JC}$	Thermal Resistance, Junction to Case, Max	1.74	3.33	°C/W
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient, Max		62.5	°C/W

# **Package Marking and Ordering Information**

Device Marking	Device	Package	Reel Size	Tape Width	Quantity
FQP10N20C	FQP10N20C	TO-220	Tube	N/A	50 units
FQPF10N20C	FQPF10N20C	TO-220F	Tube	N/A	50 units

# **Electrical Characteristics** $T_C = 25^{\circ}C$ unless otherwise noted.

Symbol	Parameter	Test Conditions	Min	Тур	Max	Unit
Off Cha	racteristics					
BV <sub>DSS</sub>	Drain-Source Breakdown Voltage	$V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$	200			V
$\Delta BV_{DSS}$ / $\Delta T_{J}$	Breakdown Voltage Temperature Coefficient $I_D = 250 \mu A$ , Referenced to 25°C			0.28		V/°C
		V <sub>DS</sub> = 200 V, V <sub>GS</sub> = 0 V			10	μΑ
I <sub>DSS</sub>	Zero Gate Voltage Drain Current	V <sub>DS</sub> = 160 V, T <sub>C</sub> = 125°C			100	μA
I <sub>GSSF</sub>	Gate-Body Leakage Current, Forward	V <sub>GS</sub> = 30 V, V <sub>DS</sub> = 0 V			100	nA
I <sub>GSSR</sub>	Gate-Body Leakage Current, Reverse	V <sub>GS</sub> = -30 V, V <sub>DS</sub> = 0 V			-100	nA
On Cha	racteristics					
V <sub>GS(th)</sub>	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_{D} = 250 \mu\text{A}$	2.0		4.0	V
R <sub>DS(on)</sub>	Static Drain-Source On-Resistance	V <sub>GS</sub> = 10 V, I <sub>D</sub> = 4.75 A	-	0.29	0.36	Ω
9 <sub>FS</sub>	Forward Transconductance	V <sub>DS</sub> = 40 V, I <sub>D</sub> = 4.75 A	\	5.5		S
	c Characteristics				T	
C <sub>iss</sub>	Input Capacitance	$V_{DS} = 25 \text{ V}, V_{GS} = 0 \text{ V},$		395	510	pF
C <sub>oss</sub>	Output Capacitance	f = 1.0 MHz		97	125	pF
C <sub>rss</sub>	Reverse Transfer Capacitance			40.5	53	pF
Switchi	ng Characteristics					
t <sub>d(on)</sub>	Turn-On Delay Time	V <sub>DD</sub> = 100 V, I <sub>D</sub> = 9.5 A,		11	30	ns
t <sub>r</sub>	Turn-On Rise Time	$R_G = 25 \Omega$		92	190	ns
t <sub>d(off)</sub>	Turn-Off Delay Time			70	150	ns
t <sub>f</sub>	Turn-Off Fall Time	(Note 4)	/	72	160	ns
$Q_g$	Total Gate Charge	V <sub>DS</sub> = 160 V, I <sub>D</sub> = 9.5 A,	/	20	26	nC
$Q_{gs}$	Gate-Source Charge	V <sub>GS</sub> = 10 V		3.1		nC
Q <sub>gd</sub>	Gate-Drain Charge	(Note 4)		10.5		nC
Drain-S	ource Diode Characteristics and	d Maximum Ratings				
I <sub>S</sub>	Maximum Continuous Drain-Source Diode Forward Current				9.5	Α
I <sub>SM</sub>	Maximum Pulsed Drain-Source Diode Forward Current				38	Α
V <sub>SD</sub>	Drain-Source Diode Forward Voltage	V <sub>GS</sub> = 0 V, I <sub>S</sub> = 9.5 A			1.5	V
t <sub>rr</sub>	Reverse Recovery Time	V <sub>GS</sub> = 0 V, I <sub>S</sub> = 9.5 A,		158		ns
Q <sub>rr</sub>	Reverse Recovery Charge	dI <sub>F</sub> / dt = 100 A/μs		0.97		μС

#### Notes

<sup>1.</sup> Repetitive Rating : Pulse width limited by maximum junction temperature.

<sup>2.</sup> L = 3.5 mH, I  $_{AS}$  = 9.5 A, V  $_{DD}$  = 50 V, R  $_{G}$  = 25  $\Omega,$  starting  $\,$  T  $_{J}$  = 25  $^{\circ}C.$ 

<sup>3.</sup> I  $_{SD} \leq$  9.5 A, di/dt  $\leq$  300 A/µs, V  $_{DD} \leq$  BV  $_{DSS,}$  starting  $\,$  T  $_{J}$  = 25°C.

<sup>4.</sup> Essentially independent of operating temperature.

# **Typical Characteristics**

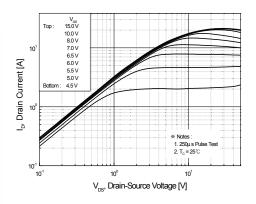


Figure 1. On-Region Characteristics

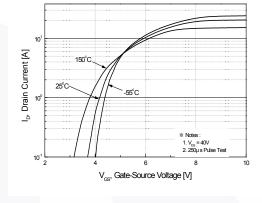


Figure 2. Transfer Characteristics

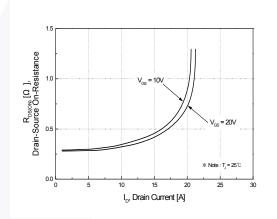


Figure 3. On-Resistance Variation vs Drain Current and Gate Voltage

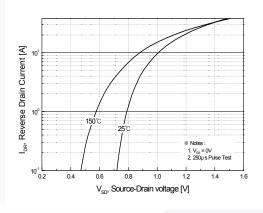


Figure 4. Body Diode Forward Voltage Variation with Source Current and Temperature

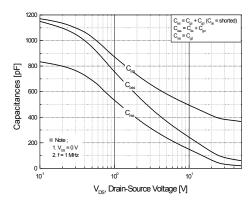


Figure 5. Capacitance Characteristics

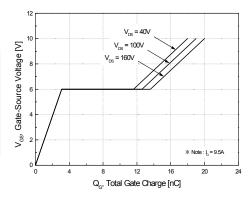


Figure 6. Gate Charge Characteristics

# Typical Characteristics (Continued)

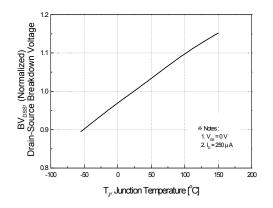


Figure 7. Breakdown Voltage Variation vs Temperature

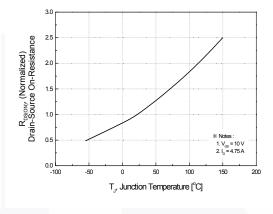


Figure 8. On-Resistance Variation vs Temperature

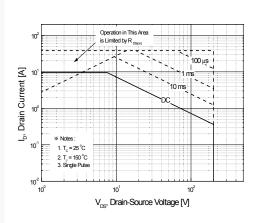


Figure 9-1. Maximum Safe Operating Area for FQP10N20C

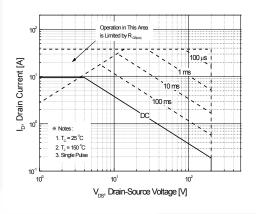


Figure 9-2. Maximum Safe Operating Area for FQPF10N20C

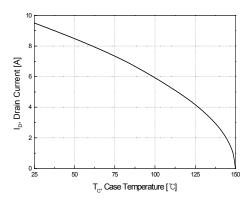


Figure 10. Maximum Drain Current vs Case Temperature

# Typical Characteristics (Continued)

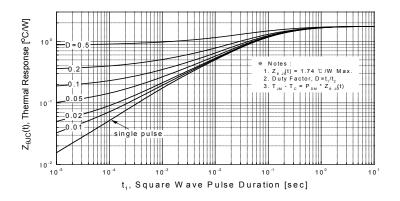


Figure 11-1. Transient Thermal Response Curve for FQP10N20C

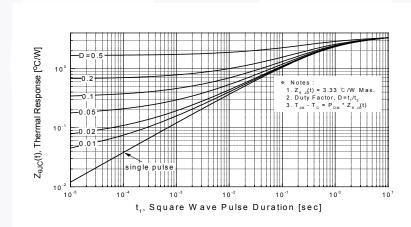


Figure 11-2. Transient Thermal Response Curve for FQPF10N20C

Figure 12. Gate Charge Test Circuit & Waveform

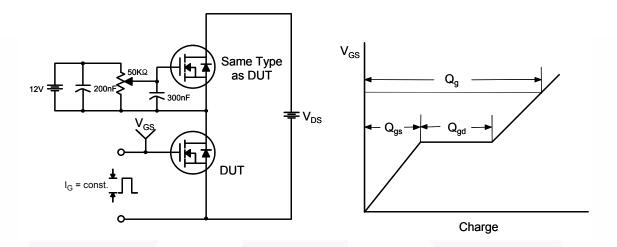


Figure 13. Resistive Switching Test Circuit & Waveforms

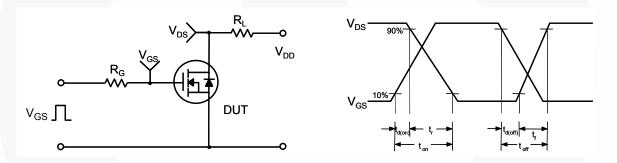
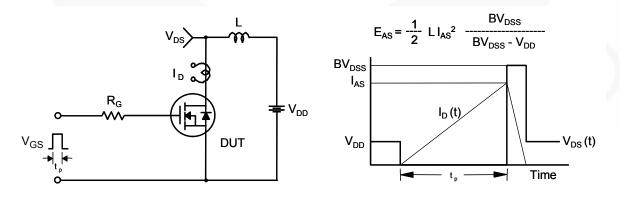


Figure 14. Unclamped Inductive Switching Test Circuit & Waveforms



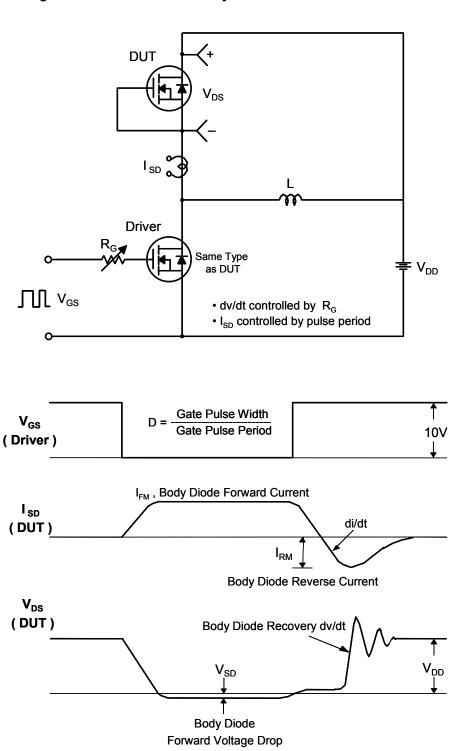


Figure 15. Peak Diode Recovery dv/dt Test Circuit & Waveforms

## **Mechanical Dimensions**

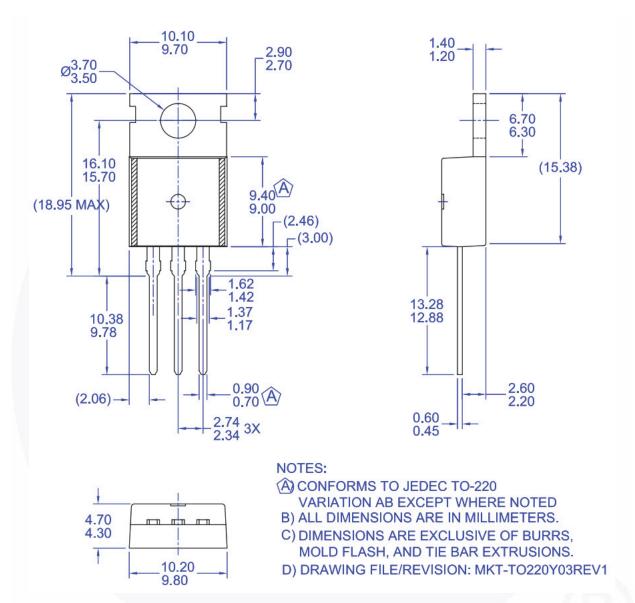


Figure 16. TO220, Molded, 3-Lead, Jedec Variation AB

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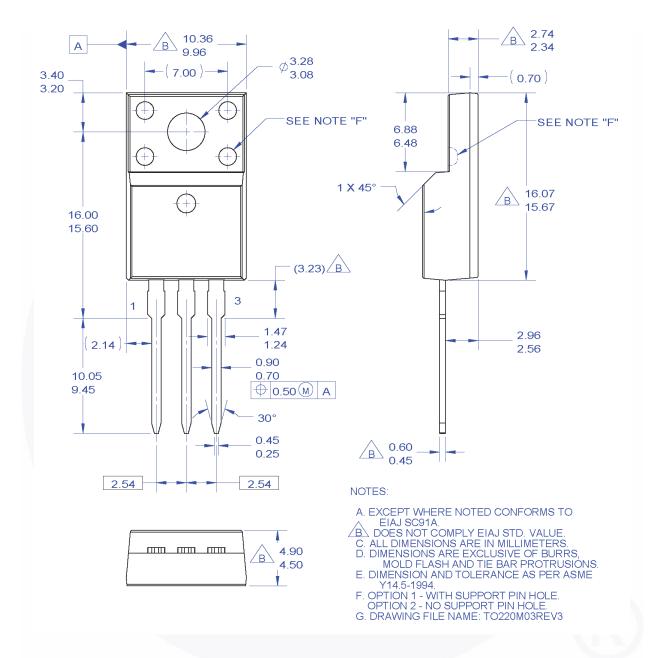


Figure 17. TO220, Molded, 3-Lead, Full Pack, EIAJ SC91, Straight Lead

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